

# ES52E9C1V-10.000M



## ITEM DESCRIPTION

Temperature Compensated Quartz Crystal Clock Oscillators TCXO (TCVCXO) Clipped Sinewave Stratum 3 3.3Vdc 10 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 10.000MHz  $\pm 0.28$ ppm Maximum -20°C to +70°C

## ELECTRICAL SPECIFICATIONS

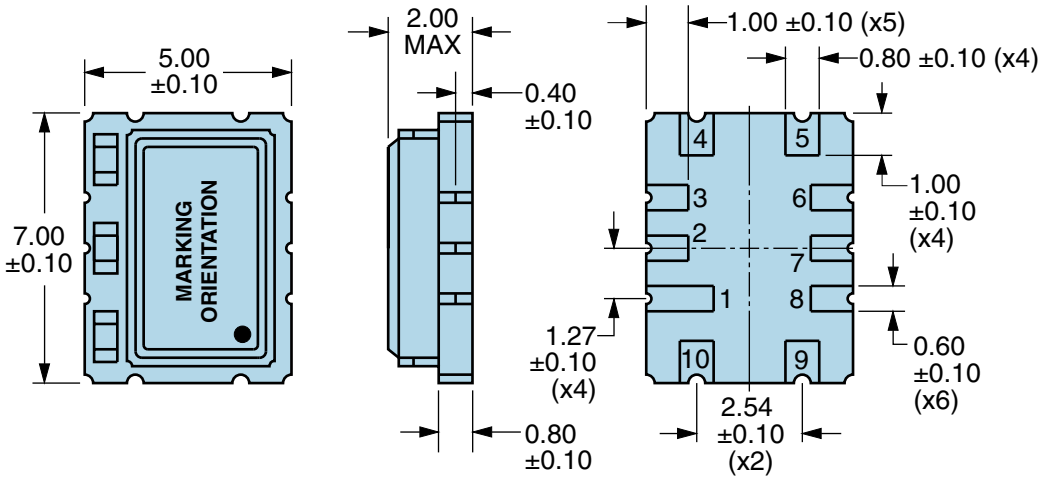
|                               |                                                                                                                                                        |
|-------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency             | 10.000MHz                                                                                                                                              |
| Total Frequency Tolerance     | $\pm 4.6$ ppm Maximum (Inclusive of Frequency Tolerance, Frequency Stability, Vdd ( $\pm 1\%$ ), Load ( $\pm 5\%$ ), solder reflow, and 20 year aging) |
| Frequency Tolerance           | $\pm 1.0$ ppm Maximum (at 25°C $\pm 2^\circ\text{C}$ , at Vdd=3.3Vdc and Vc=1.5Vdc (Pre-Reflow))                                                       |
| Frequency Stability           | $\pm 0.28$ ppm Maximum (Inclusive of Operating Temperature Range, at Vdd=3.3Vdc; $(F_{\text{max}} - F_{\text{min}})/(2 \cdot F_0)$ )                   |
| Frequency Stability vs. Aging | $\pm 3.0$ ppm over 20 Years Maximum (at 25°C)                                                                                                          |
| Operating Temperature Range   | -20°C to +70°C                                                                                                                                         |
| Supply Voltage                | 3.3Vdc $\pm 5\%$                                                                                                                                       |
| Total Holdover Stability      | $\pm 0.37$ ppm Maximum (Inclusive of Frequency Stability and 24 hours aging)                                                                           |
| Input Current                 | 2.0mA Maximum                                                                                                                                          |
| Output Voltage                | 0.8Vp-p Clipped Sinewave Minimum (External DC-Cut capacitor required, 1000pF recommended)                                                              |
| Load Drive Capability         | 10kOhms // 10pF                                                                                                                                        |
| Output Logic Type             | Clipped Sinewave                                                                                                                                       |
| Control Voltage               | 1.5Vdc $\pm 1.0$ Vdc                                                                                                                                   |
| Control Voltage Range         | 0.0Vdc to Vdd                                                                                                                                          |
| Frequency Deviation           | $\pm 5$ ppm Minimum                                                                                                                                    |
| Linearity                     | 5% Maximum                                                                                                                                             |
| Transfer Function             | Positive Transfer Characteristic                                                                                                                       |
| Input Impedance               | 100kOhms Minimum                                                                                                                                       |
| Phase Noise                   | All Values are Typical<br>-80dBc/Hz at 10Hz Offset<br>-115dBc/Hz at 100Hz Offset<br>-135dBc/Hz at 1kHz Offset<br>-145dBc/Hz at $\geq 10$ kHz Offset    |
| RMS Phase Jitter              | 1pSec Maximum ( $F_j = 12\text{kHz to } 20\text{MHz}$ )                                                                                                |
| Start Up Time                 | 10mSec Maximum                                                                                                                                         |
| Storage Temperature Range     | -40°C to +125°C                                                                                                                                        |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                      |
|------------------------------|--------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014 Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014 Condition C |
| Mechanical Shock             | MIL-STD-202, Method 213 Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210              |
| Resistance to Solvents       | MIL-STD-202, Method 215              |
| Solderability                | MIL-STD-883, Method 2003             |
| Temperature Cycling          | MIL-STD-883, Method 1010             |
| Vibration                    | MIL-STD-883, Method 2007 Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

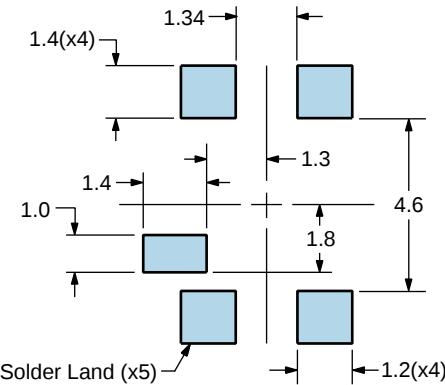


| PIN | CONNECTION      |
|-----|-----------------|
| 1   | Do Not Connect  |
| 2   | Do Not Connect  |
| 3   | Do Not Connect  |
| 4   | Ground          |
| 5   | Output          |
| 6   | Do Not Connect  |
| 7   | Do Not Connect  |
| 8   | Do Not Connect  |
| 9   | Supply Voltage  |
| 10  | Voltage Control |

| LINE | MARKING                                                                                |
|------|----------------------------------------------------------------------------------------|
| 1    | <b>EXX.XXX</b><br><i>E=Ecliptek Designator<br/>XX.XXX=Nominal<br/>Frequency in MHz</i> |
| 2    | <b>XXXXXX</b><br><i>XXXXXX=Ecliptek<br/>Manufacturing Identifier</i>                   |

Suggested Solder Pad Layout

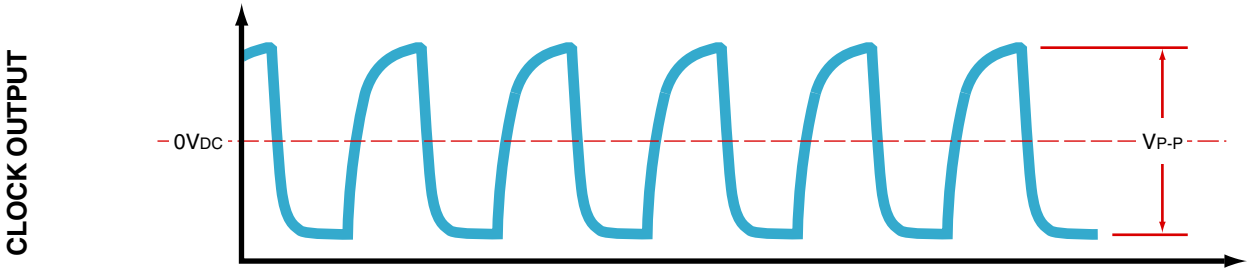
All Dimensions in Millimeters



All Tolerances are ±0.1

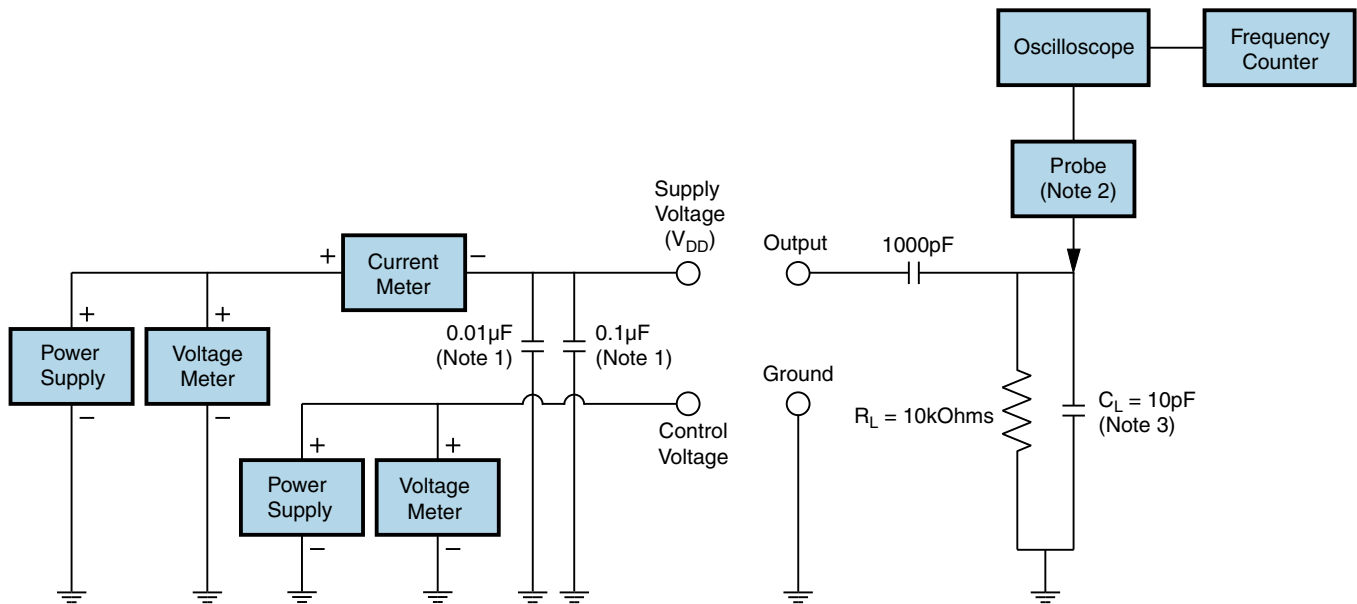
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OUTPUT WAVEFORM



# ES52E9C1V-10.000M

## Test Circuit for Control Voltage Option



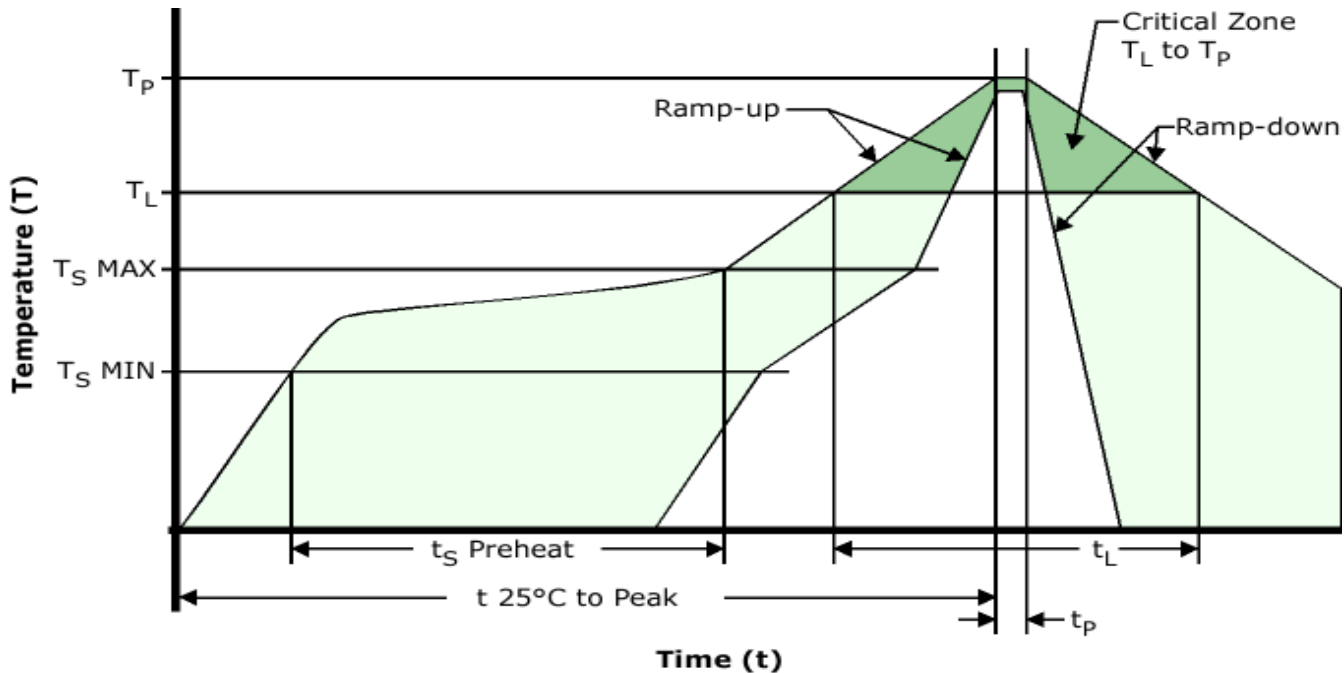
Note 1: An external  $0.01\mu\text{F}$  bypass capacitor in parallel with a  $0.1\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{M}\Omega$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



## Low Temperature Infrared/Convection 230°C

|                                                     |                    |
|-----------------------------------------------------|--------------------|
| T <sub>S</sub> MAX to T <sub>L</sub> (Ramp-up Rate) | 5°C/Second Maximum |
|-----------------------------------------------------|--------------------|

### Preheat

|                                            |                 |
|--------------------------------------------|-----------------|
| - Temperature Minimum (T <sub>S</sub> MIN) | N/A             |
| - Temperature Typical (T <sub>S</sub> TYP) | 150°C           |
| - Temperature Maximum (T <sub>S</sub> MAX) | N/A             |
| - Time (t <sub>s</sub> MIN)                | 30 - 60 Seconds |

|                                                  |                    |
|--------------------------------------------------|--------------------|
| Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> ) | 5°C/Second Maximum |
|--------------------------------------------------|--------------------|

### Time Maintained Above:

|                                 |                     |
|---------------------------------|---------------------|
| - Temperature (T <sub>L</sub> ) | 150°C               |
| - Time (t <sub>L</sub> )        | 200 Seconds Maximum |

|                                    |               |
|------------------------------------|---------------|
| Peak Temperature (T <sub>P</sub> ) | 230°C Maximum |
|------------------------------------|---------------|

|                                                 |                       |
|-------------------------------------------------|-----------------------|
| Target Peak Temperature (T <sub>P</sub> Target) | 230°C Maximum 2 Times |
|-------------------------------------------------|-----------------------|

|                                                  |                            |
|--------------------------------------------------|----------------------------|
| Time within 5°C of actual peak (t <sub>p</sub> ) | 10 Seconds Maximum 2 Times |
|--------------------------------------------------|----------------------------|

|                |                    |
|----------------|--------------------|
| Ramp-down Rate | 5°C/Second Maximum |
|----------------|--------------------|

|                                   |     |
|-----------------------------------|-----|
| Time 25°C to Peak Temperature (t) | N/A |
|-----------------------------------|-----|

|                            |         |
|----------------------------|---------|
| Moisture Sensitivity Level | Level 1 |
|----------------------------|---------|

|                  |                                                   |
|------------------|---------------------------------------------------|
| Additional Notes | Temperatures shown are applied to body of device. |
|------------------|---------------------------------------------------|

## Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

## High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)